# **Switch-mode Power** Rectifier

45 V, 20 A

## MBR20L45CTG, MBRF20L45CTG

#### **Features and Benefits**

- Low Forward Voltage
- Low Power Loss/High Efficiency
- High Surge Capacity
- 150°C Operating Junction Temperature
- 20 A Total (10 A Per Diode Leg)
- Guard-Ring for Stress Protection

#### **Applications**

- Power Supply Output Rectification
- Power Management
- Instrumentation

#### **Mechanical Characteristics:**

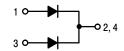
- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight (Approximately): 1.9 Grams
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 Units Per Plastic Tube
- These Devices are Pb-Free and are RoHS Compliant\*

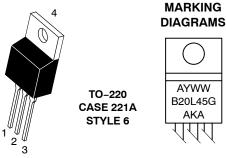


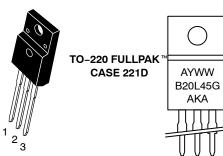
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### **DUAL SCHOTTKY BARRIER RECTIFIERS** 20 AMPERES, 45 VOLTS







B20L45 = Device Code = Assembly Location

= Year WW = Work Week = Polarity Designator **AKA** = Pb-Free Device

#### **ORDERING INFORMATION**

Device	Package	Shipping
MBR20L45CTG	TO-220 (Pb-Free)	50 Units/Rail
MBRF20L45CTG	TO-220FP (Pb-Free)	50 Units/Rail

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### MAXIMUM RATINGS (Per Diode Leg)

Rating	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	45	V	
Average Rectified Forward Current (Rated $V_R$ ) $T_C = 141$ °C	I <sub>F(AV)</sub>	10	Α	
Peak Repetitive Forward Current (Rated V <sub>R</sub> , Square Wave, 20 kHz)	I <sub>FRM</sub>	20	Α	
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I <sub>FSM</sub>	180	Α	
Operating Junction Temperature (Note 1)	T <sub>J</sub>	-55 to +150	°C	
Storage Temperature	T <sub>stg</sub>	-55 to +175	°C	
Voltage Rate of Change (Rated V <sub>R</sub> )	dv/dt	10,000	V/μs	
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteri	stic	Symbol	Value	Unit
Maximum Thermal Resistance				°C/W
(MBR20L45CTG)	Junction-to-Case	$R_{ heta JC}$	1.9	
	Junction-to-Ambient	$R_{ hetaJA}$	45	
(MBRF20L45CTG)	Junction-to-Case	$R_{ hetaJC}$	2.2	

#### **ELECTRICAL CHARACTERISTICS** (Per Diode Leg)

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 2) $ \begin{aligned} &(I_F=10 \text{ A, } T_C=25^\circ\text{C})\\ &(I_F=10 \text{ A, } T_C=125^\circ\text{C})\\ &(I_F=20 \text{ A, } T_C=25^\circ\text{C})\\ &(I_F=20 \text{ A, } T_C=125^\circ\text{C}) \end{aligned} $	VF	0.50 0.47 0.63 0.62	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_C = 25^{\circ}C$ ) (Rated DC Voltage, $T_C = 125^{\circ}C$ )	i <sub>R</sub>	0.5 170	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

<sup>1.</sup> The heat generated must be less than the thermal conductivity from Junction–to–Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

<sup>2.</sup> Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤2.0%.

#### **TYPICAL CHARACTERISTICS**

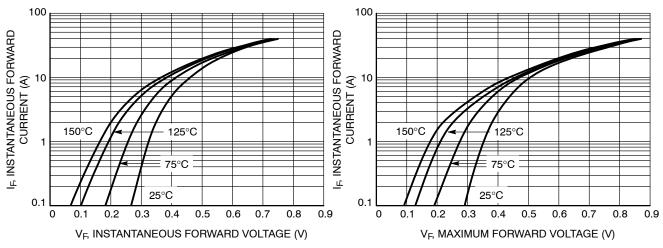
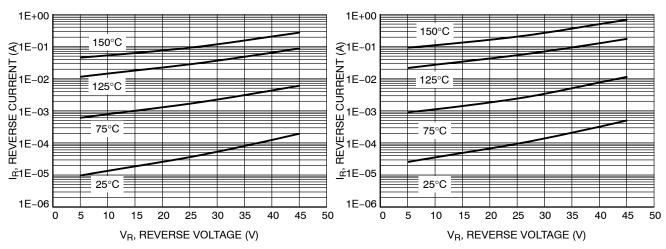


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage



**Figure 3. Typical Reverse Current** 

**Figure 4. Maximum Reverse Current** 

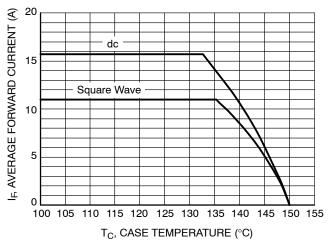


Figure 5. Current Derating

#### **TYPICAL CHARACTERISTICS**

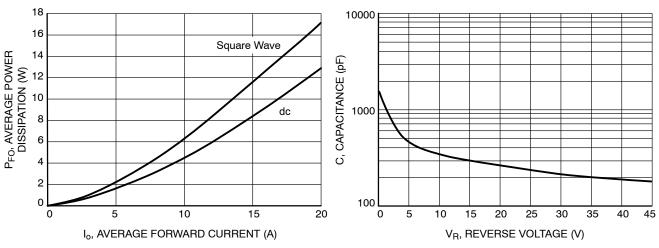


Figure 6. Forward Power Dissipation

Figure 7. Typical Capacitance

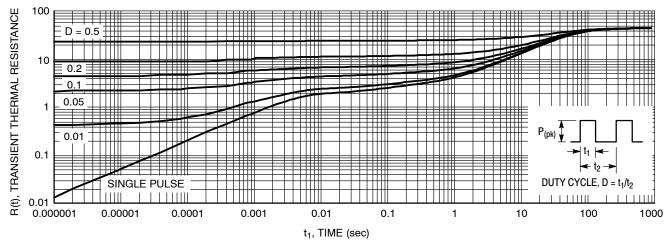


Figure 8. Thermal Response Junction-to-Ambient for MBR20L45CTG

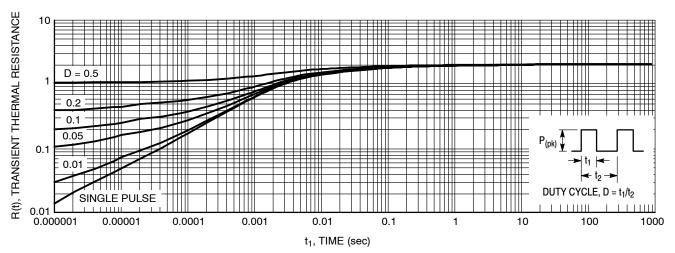


Figure 9. Thermal Response Junction-to-Case for MBR20L45CTG

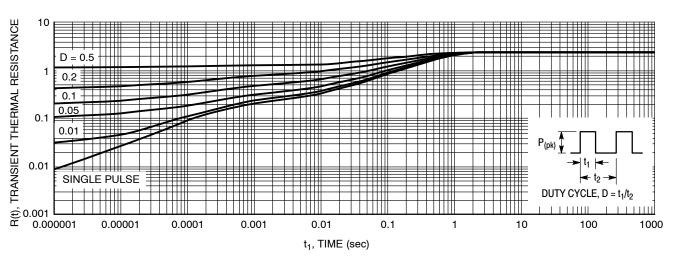
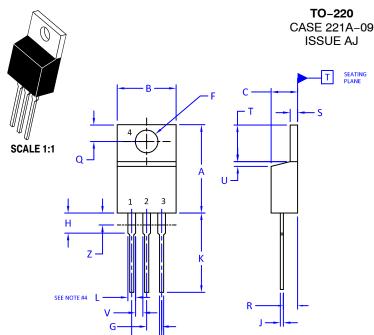


Figure 10. Thermal Response Junction-to-Case for MBRF20L45CTG

### **MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS**





#### **DATE 05 NOV 2019**

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: INCHES

NOTES:

3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

#### 4. MAX WIDTH FOR F102 DEVICE = 1.35MM

	INCHES		MILLIMETERS	
DIM	MIN.	MAX.	MIN.	MAX.
Α	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.60	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
К	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.41
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:	
PIN 1.	BASE	PIN 1.	BASE	PIN 1.	CATHODE	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	EMITTER	2.	ANODE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	COLLECTOR	3.	GATE	3.	GATE
4.	COLLECTOR	4.	EMITTER	4.	ANODE	4.	MAIN TERMINAL 2
STYLE 5:		STYLE 6:		STYLE 7:		STYLE 8:	
PIN 1.	GATE	PIN 1.	ANODE	PIN 1.	CATHODE	PIN 1.	CATHODE
2.	DRAIN	2.	CATHODE	2.	ANODE	2.	ANODE
3.	SOURCE	3.	ANODE	3.	CATHODE	3.	EXTERNAL TRIP/DELA
4.	DRAIN	4.	CATHODE	4.	ANODE	4.	ANODE
STYLE 9:		STYLE 10:		STYLE 11:		STYLE 12	:
PIN 1.	GATE	PIN 1.	GATE	PIN 1.	DRAIN	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	SOURCE	2.	SOURCE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	DRAIN	3.	GATE	3.	GATE
4.	COLLECTOR	4.	SOURCE	4.	SOURCE	4.	NOT CONNECTED

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### **MECHANICAL CASE OUTLINE**





SCALE 1:1

3. CATHODE

#### TO-220 FULLPAK CASE 221D-03 ISSUE K

**DATE 27 FEB 2009** 

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**AYWW** 

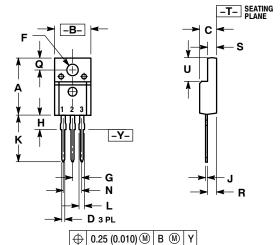
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AKA

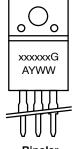
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH
- 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.617	0.635	15.67	16.12
В	0.392	0.419	9.96	10.63
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100	BSC	2.54 BSC	
Н	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200	BSC	5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

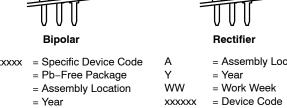
#### **MARKING DIAGRAMS**



STYLE 1: PIN 1. GATE STYLE 2: PIN 1. BASE STYLE 3: PIN 1. ANODE 2. COLLECTOR 3. EMITTER CATHODE
 ANODE 2. DRAIN 2. 3. SOURCE STYLE 6: PIN 1. MT 1 2. MT 2 3. GATE STYLE 4: PIN 1. CATHODE STYLE 5: PIN 1. CATHODE 2. ANODE 3. GATE ANODE



= Assembly Location xxxxxx = Specific Device Code G = Pb-Free Package Υ = Year Α = Assembly Location WW = Work Week Υ = Year XXXXXX = Device Code = Work Week = Pb-Free Package WW G AKA = Polarity Designator



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